



LAYER	SINGLE ENDED LINE WIDTH	100 OHM DIFF LINE WIDTH	SPACE	90 OHM DIFF LINE WIDTH	SPACE
TOP, BOTTOM	8 MILS	6.5 MILS	9 MILS	8 MILS	10 MILS

Diagram illustrating the cross-section of a 4-layer PCB structure. The layers are labeled from top to bottom:

- LAYER 1 L1 TOP
- PREPREG
- LAYER 2 L2 GND
- CORE
- LAYER 3 L15 GND
- PREPREG
- LAYER 4 L16 BOTTOM

Dimensions and materials are specified on the right side of the diagram:

- 18 UM CU + 18 UM PLATING (35 UM)
- 0.132 MM PREPREG FR-4
- 35 UM COPPER
- 0.6 MM CORE FR-4 LG 135 INC. COP.
- 35 UM COPPER
- 0.132 MM PREPREG FR-4
- 18 UM CU + 18 UM PLATING (35 UM)

A vertical dimension line on the left indicates a thickness of 1.00 MM  $\pm$  10%.

1. PRINTED CIRCUIT BOARD MADE FROM NEMA GRADE FR-4 TO 135 EPOXY LAMINATE WITH 35 UM COPPER PLATING AND 1 MM THICKNESS.
2. ALL DIMENSIONS ARE GIVEN IN MILLIMETERS EXCEPT TRACE WIDTH/SPACE.
3. CIRCUIT PATHS ARE FOR REFERENCE ONLY.
4. HOLE SIZES SHOWN ARE FINISHED DIAMETERS AFTER PLATING.
5. BOARD PLATED USING REFLOW OR SIMILAR METHOD.
6. BOARD TO HAVE GREEN SOLDER MASK ON PLATED SURFACES USING WET FILM SR100 OR SR1010 EPOXY.  
EQUIVALENT WET OR DRY FILM MAY BE USED.
7. SILKSCREEN BOARD USING WHITE INK. DISTORTION OF SILKSCREEN IS ACCEPTABLE OVER TRACES. EPOXY INK ON PLATED LANDS IS NOT ACCEPTABLE
8. THE FOLLOWING INFORMATION APPLIES TO THIS BOARD:
  - \* 4 COPPER LAYERS
  - \* 1 MM BOARD THICKNESS
  - \* REQUIRES TOP AND BOTTOM SIDE SILKSCREENS.



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Component Assembly CMP (.ASC) Rev. A